

IEIT SYSTEMS Server TS860G7

Mission-Critical application server



The TS860M7 is an eight-socket server powered by the new-generation Intel® Xeon® Scalable processors. It provides excellent computing performance and comprehensive reliability for customers' key business applications, making it suitable for application scenarios such as large transaction databases, SAP HANA, ERP & CRM, and critical application virtualization, etc

Description

Product Model	Maintenance	Cooling
TS860-M7-A0-R0-00	Rear I/O	Air cooling

Product Features

Ultimate computing and exceptional performance

- Built on the 4th Gen Intel® Xeon® Scalable processors, the TS860M7 supports up to 480 physical cores and 960 threads, 4 groups of 16GT/s high-speed UPI links and with up to 350W TDP per CPU to provide ultra-high speed interconnection for 8 CPUs. This offers excellent computing performance to customers.
- Up to 128 DDR5 RDIMMs/3DS RDIMMs, max4800MT/s, which can support scenarios of memory-intensive applications, such as SAP HANA.
- Supports heterogeneous computing and can be configured with up to 4 dual-width GPUs or 8 single-width GPUs, which can well support a variety of AI scenarios for reasoning and training.
- Balanced I/O design allocates system resources properly and reduces network access latency, thus optimizing performance. It can meet business scenarios that require fast data transmission.

High stability, reliability, and security

- Full-module design for the whole system and redundant design for critical components and chips make it ideal for mission-critical applications with high reliability requirements.
- Support PFR, the firmware protection recovery technology, and BIOS&BMC dual-redundancy design ensure stable and secure system operation.
- The memory AMT isolates faulty memory, and the MRT technology warns of memory faults in advance and memory mirroring is supported, which improves the reliability and fault tolerance capability of the memory module while securing the memory performance.
- Supports PCIe single card hot swapping and OCP card hot swapping, avoiding a single point of failure of add-in cards and reducing customer downtime for maintenance.
- Full redundancy design for wearable parts, such as PSUs Fans Drives, reduces the hardware failure rate.

Ingenious design and easy maintenance

- Modular design, front and rear access to all modules to realize tool-less maintenance for the whole system, which simplify the overall server maintenance.
- The system supports fast system status diagnostics, and a new load LED is added to the chassis front panel to display the system startup process and load status. In addition, a magnetic LCD display and bluetooth client can be configured for the system. The app displays fault code information and other information. You can view the server asset information, view and set the management IP address, and monitor the power consumption and ambient temperature of the server by using the app.
- You can configure BIOS with one-click performance settings, and up to 7 scenarios and 17 application modes are supported. This greatly improves the server configuration and deployment efficiency. One-click customization of RAS mode, you can select the RAS setting mode that suits you.

Low-carbon and high-efficiency noise reduction

- The system adopts new dual-rotor fan modules, and its optimized fan aerofoil structure significantly improves the superimposed effect of wind pressure and the air volume of the fan module as well as reduces noise, which provides high-efficient cooling experience for customers.
- Optimize the heatsinks based on the configuration. The T-shaped heatsink can reduce the fan speed by 30%~40% and the system noise, and the general heatsink can make full use of system space and well support full-length cards.
- Our unique intelligent control technology for partitions and independent airflow design in the entire system helps adjust the fan speed intelligently based on the power consumption of components in different air ducts. This eliminates temperature transmission delays, realizes energy-saving fan speed regulation and accurate air supply, and greatly improves cooling efficiency.
- This server uses innovative fan noise reduction materials that are obtained based on our hundreds of thousands of experiments and research on noise reduction materials. These materials feature efficient sound-absorbing. We are committed to producing server products with less noise for customers.
- We follow the sustainable environmental protection concept. The key components of the product meet the lead-free requirements (RoHS), and all packaging materials are recyclable.
- Titanium PSUs are supported with up to a 94% conversion efficiency

Product Specifications

Item	Description
Form Factor	6U rack server
Processor	Four or eight 4 th Gen Intel® Xeon® Scalable processors Up to 480 cores Up to 350W TDP
Chipset	Intel C741
Memory	Up to 128 DDR5 RDIMMs, max 4800MT/s 16 DIMMs per CPU and 128 DIMMs for 8 CPUs Support RDIMMs/3DS RDIMMs
Storage	Front: Up to 24 × 2.5-inch SAS/SATA/U.2 drives
	Internal: ICM supports 2 SATA/PCIe M.2 SSDs Up to 3 TF cards
Storage Controller	2 built-in raid card slots
Network	Up to 4 PCIe 5.0 x16 OCP 3.0 SFF network cards, compatible with multi-host cards in OCP form; and supports NCSI, balanced layout, and hot swap
PCIe slot	Internal: 2 SAS/RAID/Tri-mode cards Rear: 16 FHHL PCIe x16 PCIe slots, or 8 FHHL PCIe x16 PCIe slots + 4 DW/8SW GPUs, all supporting PCIe gen5
IOPort	Front: 1 × USB 2.0 port/LCD port, 1 × USB 3.0 port, and 1 × DB15 VGA port Internal: 1 × USB 3.0 port Rear: 2 × USB 3.0 ports, 1 × DB15 VGA port, 1 × COM port (Micro USB), and 1 × RJ45 management network port
Fan	8 hot-swap 8056 fan modules, N+1 rotor redundancy for the fans
Power Supply	4 × standard CRPS Platinum/Titanium PSUs with the output power of 1300W/1600W/2000W/2700W; N+M redundancy (M≤N)
System Management	Supports IPMI, SNMP, Redfish, and mobile terminal access management provided by an external Bluetooth LCD display
Security Feature	TCM/TPM 2.0, BMC/BIOS redundancy, dynamic power-capping, Intel PFR secure boot, and firmware tamper-proofing
Operating System	Microsoft Windows Server, Red Hat Enterprise Linux, SUSE Linux Enterprise Server, etc.
Dimensions (W × H × D)	With mounting ears: 482mm × 263.2mm × 870mm Without mounting ears: 448mm × 263.2mm × 820mm
Weight	Full configuration: ≤97kg (For details, refer to the White Paper)
Operating Temperature	5°C to 45°C (For more information, refer to the White Paper)